

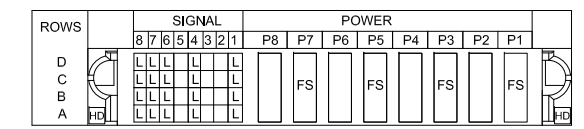
REV.	SPECIFICATION	ECN NO.	APPD.
X2		ECN231012	

Material and Plating:
Housing: LCP, UL94V-0, Black.
Power Contacts: High Conductivity Copper.
 Au+Pd/Ni or Gold Plated on Contact Area and 80u"
 Min Tin Plated on Solder Tail over Nickel 50u".
Signal Contacts : Phosphor Bronze.
 Au+Pd/Ni or Gold Plated on Contact Area and 80u"
 Min Tin Plated on Solder Tail over Nickel 50u".
Lock: Phosphor Bronze.

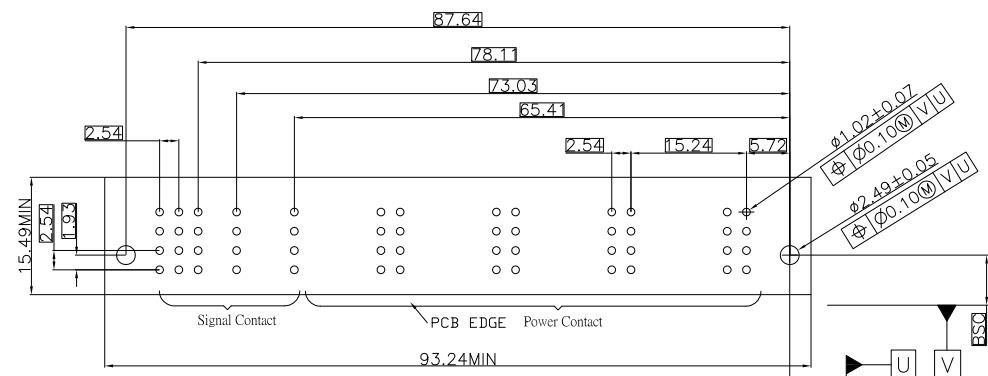
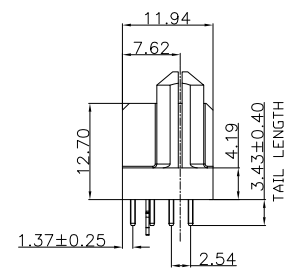
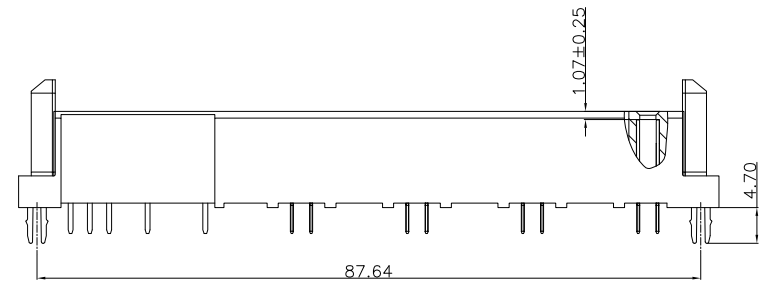
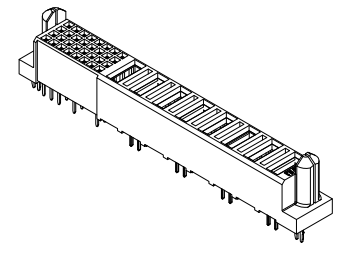
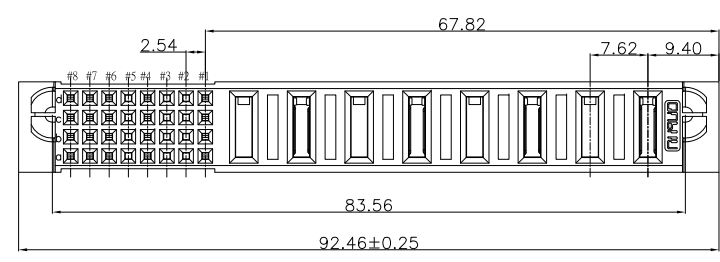
Electrical Characteristics:
Current Rating: Signal Pin: 2.5 A .
 Power Pin: 65 A(2oz x 6) .
Dielectric Withstanding Voltage:
 Signal Pin DC 1000V For 1 minute.
 Power Pin DC 2500V For 1 minute.
Insulator Resistance: Signal Pin 500MΩ max.
 Power Pin 1000MΩ max.
Contact Resistance: Signal Pin 20mΩ max.
 Power Pin 0.7mΩ max.

Operating Temperature: -40°C ~+125°C .

***RoHS Compliant**
 Note1 :
 H: High density Power---PCB Mount 5.08mm Pitch
 P: DC Power---PCB Mount 6.35mm Pitch
 A: AC Power---PCB Mount 7.62mm Pitch
 S: Signal---PCB Mount 2.54mm Pitch
 Note2:
 P2,P4,P6,P8 Without Contact.
 Row S2, S3, S5 Without Contact.



POWER CONTACT TO THE TOP DISTANCE 2.34mm,	FM
POWER CONTACT TO THE TOP DISTANCE 1.07mm,	FS
SIGNAL CONTACT 3.43 SOLDER TAIL, PD/Ni	L



P.C.Board Layout
(Tolerance:±0.05)

Series 9303- 2 S32 A08 CB30 D L A -A031 Internal Code
 2:Female Straight
 Blank: Without Contact
 Signal Contact: S xx
 No.of position
 Blank:Without Contact
 Power Contact: Hxx, Pxx , Axx
 No. of position
 A:Tray Package
 L: With Lock
 Blank: Without Lock
 D: Dip Type
 CB30: Contact Au+Pd/Ni,Dip Tin
 30: 30 u"
 Cxx: Selective Gold Plated
 10: 10 u"
 30: 30 u"

Tolerances	Dwg. No.	9303-D0000-133	Title:
x = ±0.5	Projection		9303 Series
.x = ±0.25	Unit	mm	Female Straight Dip Type
.xx = ±0.15	Scale	1:1	
	Drawn By	XS 10/13'23	

OUPIN
OUPIIN ELECTRONIC(KUNSHAN) CO., LTD.
 P/N: 9303-2S32A08CB30DLA-A031

SHEET	1/1	Ver. No.	X2
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